1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP
Package type industry code	LQFP48
Package style descriptive code	LQFP (low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026-BBC
Mounting method type	S (surface mount)
Issue date	12-5-2016
Manufacturer package code	98ASH00962A

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	7	-	mm
E	package width		-	-	7	-	mm
A	seated height		-	-	1.4	1.6	mm
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	48	-	

plastic, low profile quad; flat leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body
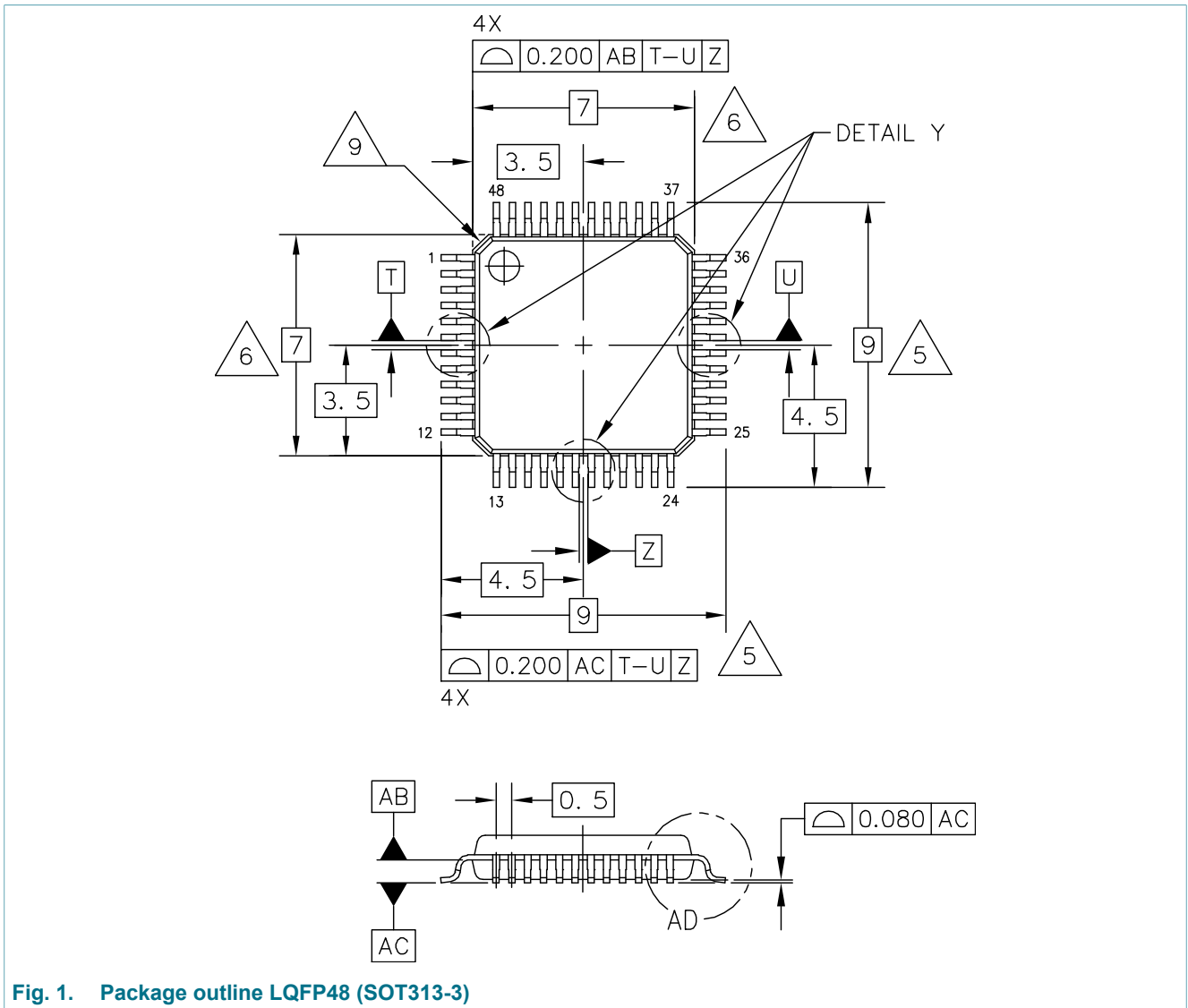
2. Package outline

Fig. 1. Package outline LQFP48 (SOT313-3)

plastic, low profile quad; flat leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body
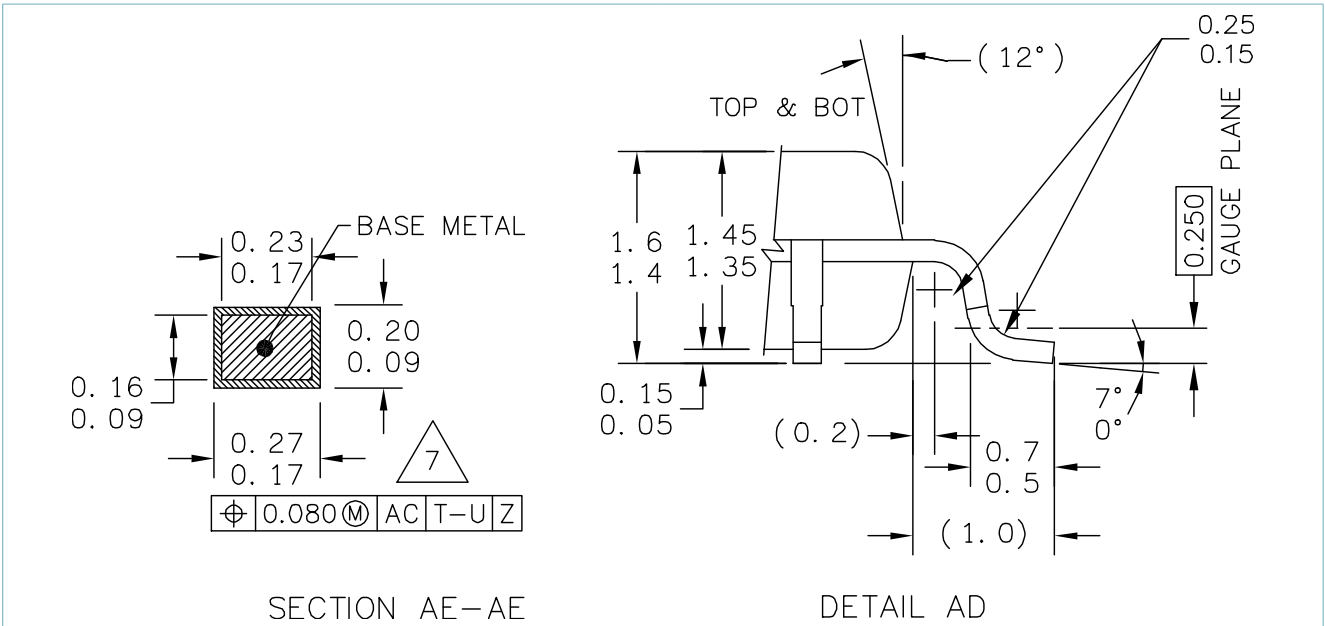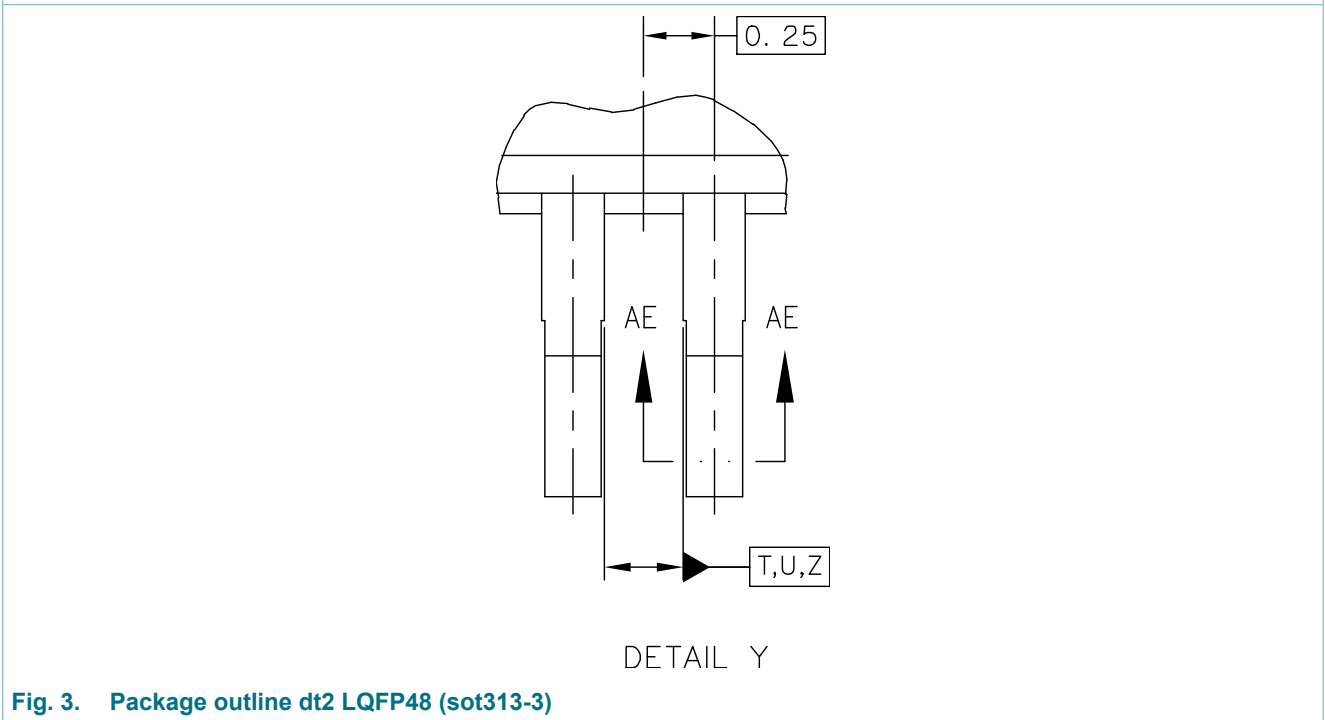

Fig. 2.   Package outline dt1 LQFP48 (sot313-3)

Fig. 3.   Package outline dt2 LQFP48 (sot313-3)

plastic, low profile quad; flat leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M−1994.

2. CONTROLLING DIMENSION: MILLIMETER.

3. DATUM PLANE AB IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

4. DATUMS T, U, AND Z TO BE DETERMINED AT DATUM PLANE AB.

5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE AC.

6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE AB.

7. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.350.

8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.

9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

Fig. 4.   Package outline note LQFP48 (sot313-3)

plastic, low profile quad; flat leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body

3. Legal information

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plastic, low profile quad; flat leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body

4. Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com
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